2 RESET

- Very Low Power Consumption . . . 2 mW Typ at $V_{DD} = 5 \text{ V}$
- Capable of Operation in Astable Mode
- **CMOS Output Capable of Swinging Rail to**
- **High Output-Current Capability** Sink 100 mA Typ Source 10 mA Typ
- Output Fully Compatible With CMOS, TTL, and MOS
- **Low Supply Current Reduces Spikes During Output Transitions**
- Single-Supply Operation From 2 V to 15 V
- Functionally interchangeable With the NE556; Has Same Pinout

description

The TLC556 series are monolithic timing circuits fabricated using the TI LinCMOS™ process, which provides full compatibility with CMOS, TTL, and MOS logic and operates at frequencies up to 2 MHz. Accurate time delays and oscillations are possible with smaller, less-expensive timing capacitors than the NE556 because of the high input impedance. Power consumption is low across the full range of power supply voltages.

Like the NE556, the TLC556 has a trigger level approximately one-third of the supply voltage and

D, J, OR N PACKAGE (TOP VIEW) 1 DISCH∏ 14 | VDD 1 THRES 2 13 2 DISCH 1 CONT 12 THRES 3 1 RESET 4 11 2 CONT 1 OUT **1** 5 10 **1** 2 RESET 1 TRIG**∏** 6 9 1 2 OUT 8 2 TRIG GND **FK PACKAGE** (TOP VIEW) THRES DISCH NC VDD 2 DISCH 2 1 20 19 1 CONT 18П 2 THRES NC NC 17 2 CONT 1 RESET 16 NC NC 15

10 11 12 13

TRIG OUT

NC-No internal connection

1 OUT

a threshold level approximately two-thirds of the supply voltage. These levels can be altered by use of the control voltage terminal. When the trigger input falls below the trigger level, the flip-flop is set and the output goes high. If the trigger input is above the trigger level and the threshold input is above the threshold level, the flip-flop is reset and the output is low. The reset input can override all other inputs and can be used to initiate a new timing cycle. If the reset input is low, the flip-flop is reset and the output is low. Whenever the output is low, a low-impedance path is provided between the discharge terminal and ground.

While the CMOS output is capable of sinking over 100 mA and sourcing over 10 mA, the TLC556 exhibits greatly reduced supply-current spikes during output transitions. This minimizes the need for the large decoupling capacitors required by the NE556.

These devices have internal electrostatic-discharge (ESD) protection circuits that prevent catastrophic failures at voltages up to 2000 V as tested under MIL-STD-883C, Method 3015. However, care should be exercised in handling these devices, as exposure to ESD may result in degradation of the device parametric performance.

All unused inputs should be tied to an appropriate logic level to prevent false triggering.

The TLC556C is characterized for operation from 0°C to 70°C. The TLC556I is characterized for operation from −40°C to 85°C. The TLC556M is characterized for operation over the full military temperature range of −55°C to 125°C.

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AVAILABLE OPTIONS

т.	V		PACK	AGE		CHIP FORM
T _A RANGE	V _{DD} RANGE	SMALL OUTLINE (D)	CHIP CARRIER (FK)	CERAMIC DIP (J)	PLASTIC DIP (N)	(Y)
O°C	2 V					
to	to	TLC556CD			TLC556CN	TLC556Y
70°C	18 V					
-40°C	3 V					
to	to	TLC556ID			TLC556IN	
85°C	18 V					
−55°C	5 V					
to	to	TLC556MD	TLC556MFK	TLC556MJ	TLC556MN	
125°C	18 V					

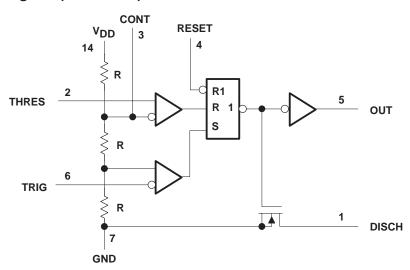
The D package is available taped and reeled. Add the suffix R to the device type (e.g., TLC556CDR).

FUNCTION TABLE

RESET VOLTAGE†	TRIGGER VOLTAGE†	THRESHOLD VOLTAGE†	ОИТРИТ	DISCHARGE SWITCH
< MIN	Irrelevant	Irrelevant	L	On
> MAX	< MIN	Irrelevant	Н	Off
>MAX	>MAX	>MAX	L	On
> MAX	> MAX	< MIN	As previously	established

[†] For conditions shown as MIN or MAX, use the appropriate value specified under electrical characteristics.

functional block diagram (each timer)



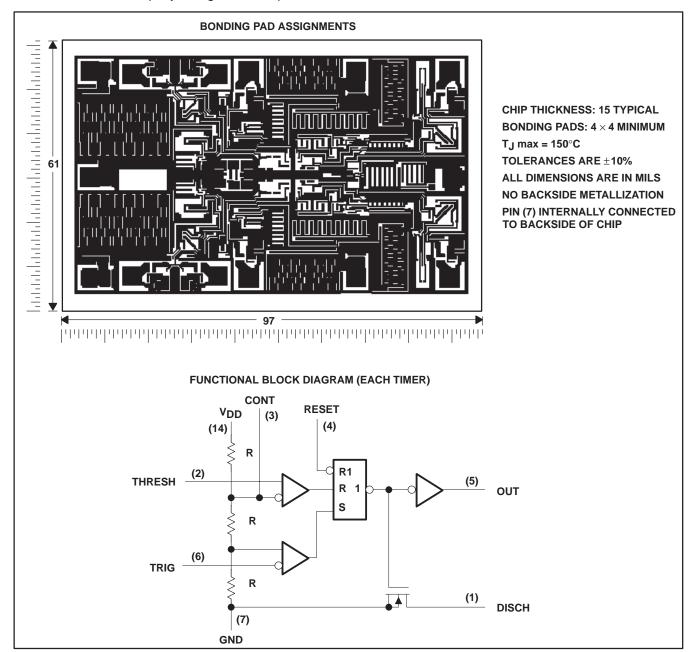
RESET can override TRIG and THRES. TRIG can override THRES.

Pin numbers shown are for the D, J, or N packages.



TLC556Y chip information

These chips, properly assembled, display characteristics similar to the TLC556 (see electrical table). Thermal compression or ultrasonic bonding may be used on the doped aluminum bonding pads. Chips may be mounted with conductive epoxy or a gold-silicon preform.



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absolute maximum ratings over operating free-air temperature (unless otherwise noted)

		TLC556C	TLC556I	TLC556M	UNIT	
Supply voltage, V _{DD} (see Note 1)	18	18	18	V		
Input voltage range, V _I		-0.3 to $V_{\mbox{DD}}$	-0.3 to $V_{\mbox{\scriptsize DD}}$	-0.3 to $V_{\mbox{DD}}$	V	
Sink current, discharge or output		150	150	150	mA	
Source current, output	15	15	15	mA		
Continuous total power dissipation		See Dissipation Rating Table				
Operating free-air temperature range		0 to 70	-40 to 85	-55 to 125	°C	
Storage temperature range		-65 to 150	-65 to 150	-65 to 150	°C	
Case temperature for 60 seconds	FK package			260		
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds			300	°C		
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260	260				

NOTE 1: All voltage values are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \leq 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
D	950 mW	7.6 mW/°C	608 mW	494 mW	N/A
FK	1375 mW	11.0 mW/°C	880 mW	715 mW	275 mW
J	1375 mW	11.0 mW/°C	880 mW	715 mW	275 mW
N	1150 mW	9.2 mW/°C	736 mW	598 mW	N/A

recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, V _{DD}		2	15	V
	TLC556C	0	70	
Operating free-air temperature range, TA	TLC556I	-40	85	°C
	TLC556M	-55	125	

electrical characteristics at specified free-air temperature, V_{DD} = 2 V for TLC556C, V_{DD} = 3 V for TLC556I

	DADAMETED	TEST	T. T	Т	LC556C		7	TLC556I		UNIT	
	PARAMETER	CONDITIONS	T _A †	MIN	TYP	MAX	MIN	TYP	MAX	UNII	
\/	Input throughold voltage		25°C	0.95	1.33	1.65	1.6	2	2.4	V	
VIT	Input threshold voltage		Full range	0.85		1.75	1.5		2.5	V	
	Threshold current		25°C		10			10		~ A	
	Threshold current		MAX		75			150		pА	
Va.	Triager veltege		25°C	0.4	0.67	0.95	0.71	1	1.29	V	
V(trigger)	Trigger voltage		Full range	0.3		1.05	0.61		1.39	V	
la i	Trigger ourrent		25°C		10			10		n A	
l(trigger)	Trigger current		MAX		75			150		pΑ	
Mr. s	Depart voltage		25°C	0.4	1.1	1.5	0.4	1.1	1.5	V	
V _(reset)	Reset voltage		Full range	0.3		1.8	0.3		1.8	V	
1	Decet comment		25°C		10			10		- 1	
(reset)	Reset current		MAX		75			150		рA	
	Control voltage (open circuit) as a percentage of supply voltage		MAX		66.7%			66.7%			
	Discharge switch on-state volt-	1 1 1	25°C		0.04	0.2		0.03	0.2	V	
	age	I _{OL} = 1 mA	Full range			0.25			0.375	V	
	Discharge switch off-state cur-		25°C		0.1			0.1		nA	
	rent		MAX		0.5			120		ΠA	
V	Lieb level autout valtage	J 200 A	25°C	1.5	1.9		1.5	1.9		V	
VOH	High-level output voltage	I _{OH} = -300 μA	Full range	1.5			2.5			V	
Vai	Low lovel output voltage	lo: -1 mA	25°C		0.07	0.3		0.07	0.3	V	
VOL	Low-level output voltage	I _{OL} = 1 mA	Full range			0.35			0.4	1 '	
la-a	Complex company	See Note 2	25°C		130	500		130	500		
IDD	Supply current	See Note 2	Full range			800			1000	μΑ	

[†] Full range is 0°C to 70°C for TLC556C and –40°C to 85°C for TLC556I.

NOTE 2: These values apply for the expected operating configurations in which THRES is connected directly to DISCH or TRIG.

TLC556, TLC556Y DUAL LinCMOS™ TIMERS

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electrical characteristics at specified free-air temperature, $V_{DD} = 5 V$

	PARAMETER	TEST	- +	٦	LC556C			TLC556I		Т	LC556M		UNIT
	PARAMETER	CONDITIONS	T _A †	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNII
l,	Input threshold		25°C	2.8	3.3	3.8	2.8	3.3	3.8	2.8	3.3	3.8	V
VIT	voltage		Full range	2.7		3.9	2.7		3.9	2.7		3.9	V
	There had a const		25°C		10			10			10		- 0
	Threshold current		MAX		75			150			5000		pА
Ţ,	T:		25°C	1.36	1.66	1.96	1.36	1.66	1.96	1.36	1.66	1.96	V
V _(trigger)	Trigger voltage		Full range	1.26		2.06	1.26		2.06	1.26		2.06	V
ĺ.	- :		25°C		10			10			10		
^I (trigger)	Trigger current		MAX		75			150			5000		pΑ
	5		25°C	0.4	1.1	1.5	0.4	1.1	1.5	0.4	1.1	1.5	.,
V _(reset)	Reset voltage		Full range	0.3		1.8	0.3		1.8	0.3		1.8	V
		1	25°C		10			10			10		
I(reset)	Reset current		MAX		75			150			5000		pΑ
	Control voltage (open circuit) as a percentage of supply voltage		MAX		66.7%			66.7%			66.7%		
	Discharge switch	10 1	25°C		0.15	0.5		0.15	0.5		0.15	0.5	
	on-state voltage	$I_{OL} = 10 \text{ mA}$	Full range			0.6			0.6		0.6		V
	Discharge switch		25°C		0.1			0.1			0.1		0
	off-state current		MAX		0.5			2			120		nA
.,	High-level output		25°C	4.1	4.8		4.1	4.8		4.1	4.8		.,
VOH	voltage	$I_{OH} = -1 \text{ mA}$	Full range	4.1			4.1			4.1			V
		0 4	25°C		0.21	0.4		0.21	0.4		0.21	0.4	
		$I_{OL} = 8 \text{ mA}$	Full range			0.5			0.5			0.6	
l.,	Low-level output		25°C		0.13	0.3		0.13	0.3		0.13	0.3	.,
VOL	voltage	. I I = 5 mA	Full range			0.4			0.4			0.45	V
		25°C		0.08	0.3		0.08	0.3		0.08	0.3		
	I _{OL} = 3.2 mA	Full range			0.35			0.35			0.4		
	Cumply surrent	See Note 2	25°C		340	700		340	700		340	700	^
IDD	Supply current	See Note 2	Full range			1000			1200			1400	μΑ

[†] Full range is 0°C to 70°C for TLC556C, -40°C to 85°C for TLC556I, and -55°C to 125°C for TLC556M.

NOTE 2: These values apply for the expected operating configurations in which THRES is connected directly to DISCH or to TRIG.



electrical characteristics at specified free-air temperature, V_{DD} = 15 V

	DADAMETER	TEST	T. T	7	LC556C			TLC556I		Т	LC556M		
	PARAMETER	CONDITIONS	T _A †	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
VIT	Input threshold voltage		25°C	9.45	10	10.55	9.45	10	10.55	9.45	10	10.55	V
٧١١	input tilleshold voltage		Full range	9.35		10.65	9.35		10.65	9.35		10.65	V
	Threshold current		25°C		10			10			10		pA
	Threshold current		MAX		75			150			5000		PΛ
V/	Trigger voltage		25°C	4.65	5	5.35	4.65	5	5.35	4.65	5	5.35	V
V _(trigger)	Trigger voltage		Full range	4.55		5.45	4.55		5.45	4.55		5.45	V
la · · · ·	Trigger current		25°C		10			10			10		pА
I(trigger)	ringger current		MAX		75			150			5000		PΛ
V/ 0	Reset voltage		25°C	0.4	1.1	1.5	0.4	1.1	1.5	0.4	1.1	1.5	V
V _(reset)	iteset voltage		Full range	0.3		1.8	0.3		1.8	0.3		1.8	V
1/	Reset current		25°C		10			10			10		pA
I(reset)	Reset current		MAX		75			150			5000		PΑ
	Control voltage (open circuit) as a percentage of supply voltage		MAX		66.7%			66.7%			66.7%		
	Discharge switch on-	I _{OL} = 100 mA	25°C		0.8	1.7		0.8	1.7		0.8	1.7	.,
	state voltage		Full range			1.8			1.8			1.8	V
	Discharge switch off-		25°C		0.1			0.1			0.1		A
	state current		MAX		0.5			2			120		nA
		1 10 mA	25°C	12.5	14.2		12.5	14.2		12.5	14.2		
		I _{OH} = -10 mA	Full range	12.5			12.5			12.5			
V	High-level output	I _{OH} = -5 mA	25°C	13.5	14.6		13.5	14.6		13.5	14.6		V
VOH	voltage	10H = -3 IIIA	Full range	13.5			13.5			13.5			v
		lou - 1 mA	25°C	14.2	14.9		14.2	14.9		14.2	14.9		
		I _{OH} = -1 mA	Full range	14.2			14.2			14.2			
		100 m A	25°C		1.28	3.2		1.28	3.2		1.28	3.2	
		I _{OL} = 100 mA	Full range			3.6			3.7			3.8	
V	Low-level output	1 F0 m 1	25°C		0.63	1		0.63	1		0.63	1	
VOL	voltage	IOI = 50 mA	Full range			1.3			1.4			1.5	V
	l	25°C		0.12	0.3		0.12	0.3		0.12	0.3	1	
	$I_{OL} = 10 \text{ mA}$	Full range			0.4			0.4			0.45		
loo	Supply current	25	25°C		0.72	1.2		0.72	1.2		0.72	1.2	mΛ
IDD	Supply current	See Note 2	Full range			1.6			1.8			2	mA

[†] Full range is 0°C to 70°C for TLC556C, -40°C to 85°C for TLC556I, and -55°C to 125°C for TLC556M.

NOTE 2: These values apply for the expected operating configurations in which THRES is connected directly to DISCH or TRIG.

electrical characteristics, $V_{DD} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VIT	Input threshold voltage		2.8	3.3	3.8	V
	Threshold current			10		pА
V _(trigger)	Trigger voltage		1.36	1.66	1.96	V
I _(trigger)	Trigger current			10		pА
V _(reset)	Reset voltage		0.4	1.1	1.5	V
I _(reset)	Reset current			10		pА
	Discharge switch on-state voltage	I _{OL} = 10 mA		0.15	0.5	V
	Discharge switch off-state current			0.1		nA
Vон	High-level output voltage	$I_{OH} = -1 \text{ mA}$	4.1	4.8		V
		$I_{OL} = 8 \text{ mA}$		0.21	0.4	
VOL	Low-level output voltage	$I_{OL} = 5 \text{ mA}$		0.13	0.3	V
		I _{OL} = 2.1 mA		0.08	0.3	
I _{DD}	Supply current	See Note 2		3.40	700	μΑ

NOTE 2: These values apply for the expected operating configurations in which THRES is connected directly to DISCH or TRIG.

operating characteristics, V_{DD} = 5 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TES ⁻	CONDITIONS	MIN	TYP	MAX	UNIT
	Initial error of timing interval †	$V_{DD} = 5 \text{ V to } 15 \text{ V},$	$R_A = R_B = 1 \text{ k}\Omega \text{ to } 100 \text{ k}\Omega$		1%	3%	
	Supply voltage sensitivity of timing interval	$C_T = 0.1 \mu F$,	See Note 3		0.1	0.5	%/V
t _r	Output pulse rise time	D. 40 MO	C. 10 pF		20	75	
t _f	Output pulse fall time	$R_L = 10 M\Omega$,	C _L = 10 pF		15	60	ns
fmax	Maximum frequency in astable mode	$R_A = 470 \Omega,$ $C_T = 200 pF,$	$R_B = 200 \Omega$, See Note 3	1.2	2.1		MHz

[†] Timing interval error is defined as the difference between the measured value and the average value of a random sample from each process run.

NOTE 3: R_A , R_B , and C_T are as defined in Figure 3.



TYPICAL CHARACTERISTICS

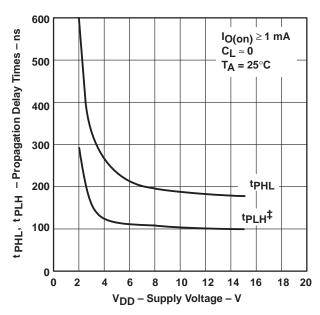
DISCHARGE SWITCH ON-STATE RESISTANCE

FREE-AIR TEMPERATURE 100 70 $V_{DD} = 2 \text{ V, I}_{O} = 1 \text{ mA}$ Discharge Switch On-State Resistance – 40 $V_{DD} = 5 \text{ V, } I_{O} = 10 \text{ mA}$ 20 $V_{DD} = 15 \text{ V}, I_{O} = 100 \text{ mA}$ 10 7 4 2 -75 -50 -25 25 75 100 T_A - Free-Air Temperature - °C

Figure 1

PROPAGATION DELAY TIMES (TO DISCHARGE OUTPUT FROM TRIGGER AND THRESHOLD SHORTED TOGETHER)

vs SUPPLY VOLTAGE



[‡]The effects of the load resistance on these values must be taken into account separately.

Figure 2



APPLICATION INFORMATION

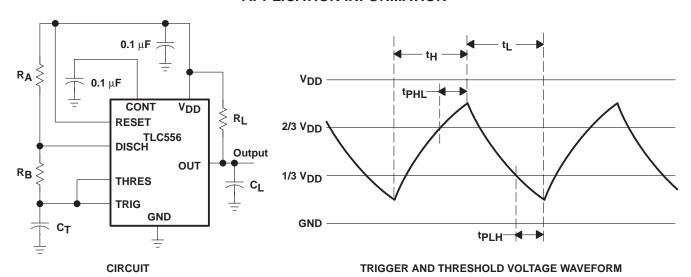


Figure 3. Astable Operation

Connecting the trigger input to the threshold input, as shown in Figure 3, causes the timer to run as a multivibrator. The capacitor C_T charges through R_A and R_B to the threshold voltage level (approximately 0.67 V_{DD}) and then discharges through R_B only to the value of the trigger voltage level (approximately 0.33 V_{DD}). The output is high during the charging cycle (t_H) and low during the discharge cycle (t_L). The duty cycle is controlled by the values of R_A , and R_B , and C_T , as shown in the equations below.

$$\begin{array}{l} t_{H} \approx C_{T} \; (R_{A} \; + \; R_{B}) \; \text{In 2} \quad (\text{In 2} = 0.693) \\ \\ t_{L} \approx C_{T} \; R_{B} \; \text{In 2} \\ \\ \text{Period} \; = \; t_{H} \; + \; t_{L} \approx C_{T} \; (R_{A} \; + \; 2R_{B}) \; \text{In 2} \\ \\ \text{Output driver duty cycle} \; = \; \frac{t_{L}}{t_{H} \; + \; t_{L}} \; \approx \; 1 \; - \; \frac{R_{B}}{R_{A} \; + \; 2R_{B}} \\ \\ \text{Output waveform duty cycle} \; = \; \frac{t_{H}}{t_{H} \; + \; t_{L}} \; \approx \; \frac{R_{B}}{R_{A} \; + \; 2R_{B}} \end{array}$$

The 0.1-μF capacitor at CONT in Figure 3 decreases the period by about 10%.

The formulas shown above do not allow for any propagation delay from the trigger and threshold inputs to the discharge output. These delay times add directly to the period and create differences between calculated and actual values that increase with frequency. In addition, the discharge output resistance r_{on} adds to R_B to provide another source of error in the calculation when R_B is very low or r_{on} is very high.

The equations below provide better agreement with measured values.

$$t_{H} = C_{T} (R_{A} + R_{B}) \text{ In } \left[3 - \exp\left(\frac{-t_{PLH}}{C_{T} (R_{B} + r_{on})}\right) \right] + t_{PHL}$$

$$t_{L} = C_{T} (R_{B} + r_{on}) \text{ In } \left[3 - \exp\left(\frac{-t_{PHL}}{C_{T} (R_{A} + R_{B})}\right) \right] + t_{PLH}$$



APPLICATION INFORMATION

The preceding equations and those given earlier are similar in that a time constant is multiplied by the logarithm of a number or function. The limit values of the logarithmic terms must be between In 2 at low frequencies and In 3 at extremely high frequencies. For a duty cycle close to 50%, an appropriate constant for the logarithmic

terms can be substituted with good results. Duty cycles less than 50% $\frac{t_H}{t_H + t_L}$ will require that $\frac{t_H}{t_L}$ <1 and

possibly $R_A \le r_{on}$. These conditions can be difficult to obtain.

In monostable applications, the trip point of the trigger input can be set by a voltage applied to CONT. An input voltage between 10% and 80% of the supply voltage from a resistor divider with at least 500- μ A bias provides good results.

PACKAGE OPTION ADDENDUM

26-Mar-2010 www.ti.com

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-89503022A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8950302CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
TLC556CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC556CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC556CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC556CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC556CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC556CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC556ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC556IDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC556IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC556IDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC556IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC556INE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC556MD	ACTIVE	SOIC	D	14	50	TBD	CU NIPDAU	Level-1-220C-UNLIM
TLC556MDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC556MDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC556MDRG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC556MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TLC556MJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
TLC556MJB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
TLC556MN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

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for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

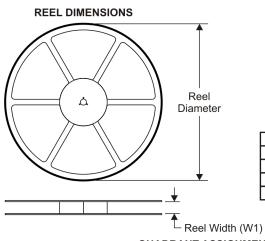
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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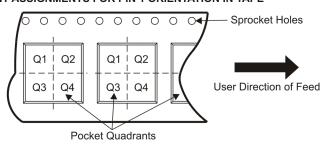
TAPE AND REEL INFORMATION



TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

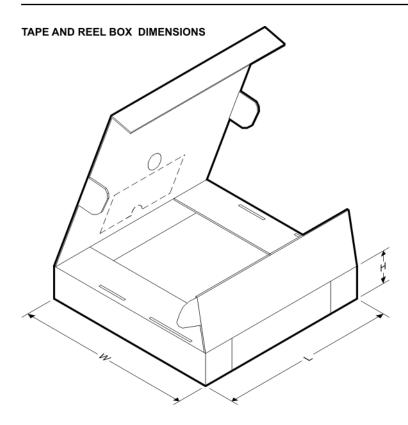
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC556CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC556IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC556CDR	SOIC	D	14	2500	346.0	346.0	33.0
TLC556IDR	SOIC	D	14	2500	346.0	346.0	33.0

14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



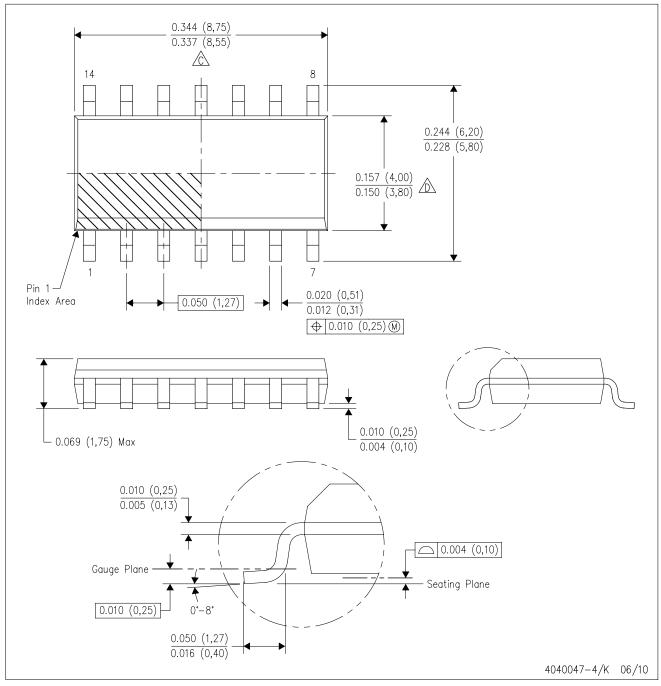
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



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